PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5664369

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
KEUN PARK	07/31/2019
BONA GOO	07/31/2019

RECEIVING PARTY DATA

Name:	FOUNDATION FOR RESEARCH AND BUSINESS, SEOUL NATIONAL UNIVERSITY OF SCIENCE AND TECHNOLOGY
Street Address:	(GONGNEUNG-DONG, SEOUL NATIONAL UNIVERSITY OF SCIENCE AND TECHNOLOGY) 232
Internal Address:	GONGNEUNG-RO, NOWON-GU,
City:	SEOUL
State/Country:	KOREA, REPUBLIC OF
Postal Code:	01811

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16528223

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Email: lmartino@mendelip.com
Correspondent Name: MENDELSOHN DUNLEAVY, P.C.
Address Line 1: 1500 JOHN F. KENNEDY BLVD.
Address Line 2: TWO PENN CENTER, SUITE 312
Address Line 4: PHILADELPHIA, PENNSYLVANIA 19102

ATTORNEY DOCKET NUMBER:	JSIP-1072US
NAME OF SUBMITTER:	GARTH M. DAHLEN
SIGNATURE:	/Garth M. Dahlen/
DATE SIGNED:	08/12/2019

Total Attachments: 3
source=JSIP1072US_ExecutedAssignment#page1.tif
source=JSIP1072US_ExecutedAssignment#page2.tif

ASSIGNMENT

WHEREAS, **Keun Park,** residing at #240-904, Recents Apt., 135, Olympic-ro, Songpa-gu, Seoul 05502 Republic of Korea and **Bona Goo**, residing at #302-2203, Paragon Apt., 428, Yudeungcheondong-ro, Jung-gu, Daejeon 34889 Republic of Korea (hereinafter referred to as, "the Assignors") are the inventors of certain invention(s) or improvement(s) as described and/or claimed in Korean Patent Application No. 10-2019-0025118, filed March 5, 2019 entitled **"FOUR-DIMENSIONAL PRINTING METHOD USING THERMAL ANISOTROPY AND THERMAL TRANSFORMATION, AND THE RESULTING PRODUCT"**, for which we will make application(s) for Letters Patent to the United States of America ("United States"), entitled, **"FOUR-DIMENSIONAL PRINTING METHOD USING THERMAL ANISOTROPY AND THERMAL TRANSFORMATION, AND THE RESULTING PRODUCT",** and for which we filed U.S. Patent Application No. 16/528,223 on July 31, 2019, having a docket number JSIP-1072US. If not already inserted, I hereby authorize and request the law firm of Mendelsohn Dunleavy, PC, of 1500 John F. Kennedy Blvd., Suite 312, Philadelphia, PA 19102, to insert herein the filing date(s) and application number(s) of said application(s) when known.

WHEREAS, **FOUNDATION FOR RESEARCH AND BUSINESS, SEOUL NATIONAL UNIVERSITY OF SCIENCE AND TECHNOLOGY,** having its principal place of business at (Gongneung-dong, Seoul National University of Science and Technology) 232, Gongneung-ro, Nowon-gu, Seoul 01811 Republic of Korea, (hereinafter referred to as the "Assignee"), is desirous of acquiring the entire right, title and interest in and to the said Patent Property in any and all countries;

NOW, THEREFORE, for and in consideration of the sum of One Dollar ($1.00) to us in hand paid by said Assignee, and other good and valuable consideration, the receipt of which is hereby acknowledged, we, the said Assignors, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over to said Assignee, the entire right, title and interest in and to said invention(s) or improvement(s) and said application(s) including the right to claim priority to the application(s) in any application entitled to claim such priority under national law, international conventions, treaties or otherwise, and any and all continuations, divisions and renewals of and substitutes for said application(s), and in, to and under any and all Letters Patent which may be granted on or as a result thereof in the United States and any and all other countries, and any reissue or reissues or extension or extensions of said Letters Patent, and assign to and authorize said Assignee, to file in our name applications for Letters Patent in all countries, the same to be held and enjoyed by said Assignee, it's successors, assigns, nominees or legal representatives, to the full end of the term or terms for which said Letters Patent respectively may be granted, reissued or extended, as fully and entirely as the same would have been held and enjoyed by us had this assignment, sale and transfer not been made.

AND we hereby covenant that we have full right to convey the entire interest herein assigned, and that we have not executed and will not execute any agreement in conflict herewith, and we further covenant and agree that we will each time a request is made and without undue delay, execute and deliver all such papers as may be necessary or desirable to perfect the title to said inventions or improvements, said application and said Letters Patent to said assignee, its successors, assigns, nominees, or legal representatives, and I agree to communicate to said assignee or to its nominee all known facts respecting said inventions or improvements, said application and said Letters Patent, to testify in any legal proceedings, to sign all lawful papers, to execute all disclaimers and divisional, continuing and reissue applications, to make all rightful oaths, and generally to do everything possible to aid said assignee, its successors, assigns, nominees and legal representatives to obtain and enforce for its or their own benefit proper patent protection for said inventions or improvements in the United States.

AND we hereby authorize and request the Director of Patents and Trademarks of the United States to issue to said assignee, as assignee of the entire right, title and interest, any and all Letters Patent for said inventions or improvements, including any and all Letters Patent of the United States which may be issued and granted on or as a result of the application aforesaid, in accordance with the terms of this assignment.

IN WITNESS WHEREOF, I have hereunto set my hand and seal.

Dated: July 31, 2019 Keun Park (L.S.)

Keun Park

IN WITNESS WHEREOF, I have hereunto set my hand and seal.

Dated: July 31, 2019

Bona Goo (L.S.)

Bona Goo